Form PTO-1449 U.S. Department of Commerce Patent and Trademark Office

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

Honeywell Ref. No.

H0004213

Serial No.

10/811,767

MBHB Case No. 06-240

Applicant: Keyser et al.

Filing Date:

March 29, 2004

Group: 2822

U.S. PROVISIONAL PATENT APPLICATION DOCUMENTS

Examiner Initial	No.	Document Number	Date	Name	Class	Subclass	Filing Date
	1.	60/863,778		Keyser et al.			10/31/06
	2.	60/863,766		Keyser et al.			10/31/06
	3.	60/831,181		Keyser			7/14/06
	4.	60/611,210		Keyser et al.			9/17/04

U.S. PUBLISHED PATENT APPLICATION DOCUMENTS

Examiner Initial	No.	Document Number	Date	Name	Class	Subclass	Filing Date
	5.	2002/0003650 A1	1/10/02	Usami et al.	359	248	7/2/01
	6.	2002/0185675 A1	12/12/02	Furukawa	257	327	6/6/01
	7.	2003/0026513 A1	2/6/03	Deliwala	385	2	5/17/01
	8.	2003/0026571 A1	2/6/03	Bazylenko	385	129	7/31/01
	9.	2003/0063364 A1	4/3/03	Kambe	359	245	9/30/02
	10.	2003/0081924 A1	5/1/03	Yegnanarayanan et al.	385	132	10/31/01
	11.	2003/0102079 A1	6/5/03	Kalvesten et al.	156	299	1/6/03
	12.	2003/0151793 A1	8/14/03	Sugiyama et al.	359	279	11/1/02
	13.	2003/0184950 A1	10/2/03	Nakamura	361	303	1/28/03
	14.	2003/0207215 A1	11/6/03	Xu et al.	430	321	1/8/03
	15.	2003/0223671 A1	12/4/03	Morse	385	14	5/31/02
	16.	2004/0002197 A1	1/1/04	Fathimulla et al.	438	455	7/1/02
	17.	2004/0021157 A1	2/5/04	Yue et al.	257	288	7/31/03
	18.	2004/0041232 A1	3/4/04	Keyser	257	516	8/29/02
	19.	2004/0126051 A1	7/1/04	Bruel	385	14	1/8/04
	20.	2004/0151463 A1	8/5/04	Talin et al.	385	131	2/3/03
	21.	2004/0190826 A1	9/30/04	Ghiron et al.	385	36	9/23/03
	22.	2004/0208454 A1	10/21/04	Montgomery et al.	385	50	3/8/04
	23.	2005/0123259 A1	6/9/05	Gunn, III et al.	385	129	1/14/05
	24.	2005/0152658 A1	7/14/05	Keyser	385	129	1/12/04
	25.	2005/0175286 A1	8/11/05	Patel et al.	385	43	2/10/04

Examiner	Date Considered
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Examiner Initial	No.	Document Number	Date	Name	Class	Subclass	Filing Date
	26.	2005/0207691 A1	9/22/05	Keyser et al.	385	1	8/10/04
	27.	2005/0207704 A1	9/22/05	Keyser et al.	385	40	8/10/04
	28.	2005/0214989 A1	9/29/05	Keyser	438	155	3/29/04
	29.	2006/0038144 A1	2/23/06	Maddison	250	559.05	8/23/04
	30.	2006/0063679 A1	3/23/06	Yue et al.	505	190	9/13/05
	31.	2007/0109549 A1	5/17/07	Sanders et al.	356	469	11/17/05
	32.	2007/0133003 A1	6/14/07	Sanders et al.	356	461	12/9/05
	33.	2007/0101927 A1	5/10/07	Keyser et al.	117	20	11/10/05

U.S. PATENT DOCUMENTS

Examiner Initial	No.	Document Number	Date	Name	Class	Subclass	Filing Date
	34.	4,234,357	11/18/80	Scheppele	148	1.5	7/16/79
	35.	4,315,693	2/16/82	Walker	356	350	12/31/79
	36.	4,673,293	6/16/87	Sanders	356	350	1/31/85
	37.	4,886,345	12/12/89	Popek	350	355	8/5/88
	38.	4,958,898	9/25/90	Friedman et al.	350	96.14	3/15/89
	39.	5,029,978	7/9/91	Curtis et al.	350	96.29	8/14/89
	40.	5,090,810	2/25/92	Malvern	356	350	4/18/90
	41.	5,143,577	9/1/92	Haas et al.	156	625	2/8/91
	42.	5,163,118	11/10/92	Lorenzo et al.	385	132	8/26/88
	43.	5,383,048	1/17/95	Seaver	359	279	2/3/93
	44.	5,408,566	4/18/95	Eda et al.	385	131	4/21/93
	45.	5,429,981	7/4/95	Gardner et al.	437	60	6/30/94
	46.	5,793,060	8/11/98	Morikawa	257	85	4/21/97
	47.	5,841,931	11/24/98	Foresi et al.	385	131	11/26/96
	48.	5,861,651	1/19/99	Brasen et al.	257	411	2/28/97
	49.	5,908,305	6/1/99	Crampton et al.	438	141	5/22/98
	50.	6,063,299	5/16/00	Drake et al.	216	24	1/13/99
	51.	6,147,362	11/14/00	Keyser	257	59	3/17/97
	52.	6,270,604 B1	8/7/01	McCallion et al.	156	99	7/23/98

Examiner	Date Considered
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Form PTO-1449 U.S. Department of Commerce Patent and Trademark Office

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Examiner Initial	No.	Document Number	Date	Name	Class	Subclass	Filing Date
	53.	6,311,003 B1	10/30/01	Dubey et al.	385	130	2/24/99
	54.	6,323,985 B1	11/27/01	Maloney	359	248	12/30/98
	55.	6,372,609 B1	4/16/02	Aga et al.	438	459	10/8/99
	56.	6,418,999 B1	7/16/02	Yanagita et al.	156	584	12/15/98
	57.	6,493,089 B2	12/10/02	Numai	356	461	10/18/99
	58.	6,566,155 B1	5/20/03	Numai	438	31	4/18/00
	59.	6,603,166 B2	8/5/03	Fechner et al.	257	301	11/27/01
	60.	6,627,954 B1	9/30/03	Seefeldt	257	350	3/19/99
	61.	6,656,747 B2	12/2/03	Sameshima	438	3	8/14/01
	62.	6,671,443 B2	12/30/03	Deliwala	385	125	2/19/02
	63.	6,743,662 B2	6/1/04	Fathimulla et al.	438	118	7/1/02
	64.	6,748,125 B2	6/8/04	Deliwala	385	2	5/17/01
	65.	6,816,636 B2	11/9/04	Cole et al.	385	10	9/12/01
	66.	6,819,814 B2	11/16/04	Forrest et al.	385	14	8/15/03
	67.	6,826,320 B2	11/30/04	Deliwala	385	14	2/19/02
	68.	6,850,683 B2	2/1/05	Lee et al.	385	129	6/7/01
	69.	6,868,214 B1	3/15/05	Sakata et al.	385	129	7/26/00
	70.	6,869,881 B1	3/22/05	Deliwala	438	689	2/15/02
	71.	6,888,219 B2	5/3/05	Keyser	257	532	8/29/02
	72.	6,890,450 B2	5/10/05	Naydenkov et al.	216	24	9/14/01
	73.	6,891,685 B2	5/10/05	Deliwala et al.	359	831	11/10/01
	74.	6,895,136 B2	5/17/05	Deliwala	385	14	7/13/04
	75.	6,912,330 B2	6/28/05	Deliwala	385	14	11/10/01
	76.	6,917,727 B2	7/12/05	Gunn, III et al.	385	14	9/9/02
	77.	6,919,238 B2	7/19/05	Bohr	438	166	7/29/02
	78.	6,944,369 B2	9/13/05	Deliwala	385	30	2/12/02
	79.	6,963,118 B2	11/8/05	Deliwala et al.	257	428	12/16/03
	80.	7,003,196 B2	2/21/06	Ghiron et al.	385	36	9/7/04
	81.	7,079,742 B1	7/18/06	Gunn, III et al.	385	129	7/15/05
	82.	7,118,682 B2	10/10/06	Patel et al.	216	24	3/23/04
	83.	7,149,388 B2	12/12/06	Keyser et al.	385	40	8/10/04
	84.	7,177,489 B2	2/13/07	Keyser et al.	385	1	8/10/04

Examiner	Date Considered

Form PTO-1449 U.S. Department of Commerce

Patent and Trademark Office

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Examiner Initial	No.	Document Number	Date	Name	Class	Subclass	Filing Date
	85.	7,217,584 B2	5/15/07	Yue et al.	438	31	8/10/04

FOREIGN PATENT DOCUMENTS

Examiner Initial	No.	Document Number	Date	Country	Class	Subclass	Trans Yes	lation No
	86.	JP404154178a						Х
	87.	06029314	4/2/94	Japan	H01L	21/336		
	88.	2 355 312 A	4/18/01	UK	G01B	6/12		
	89.	WO 02/069026 A2	9/6/02	PCT	G02F	1/025		
	90.	WO 04/095112 A2	11/4/04	PCT	G02F			

OTHER DOCUMENTS - Including Author, Title, Date, Pertinent Pages, Etc.

Examiner Initial	No.	
	91.	Application No. 11/342,158 filed on January 27, 2006.
	92.	Application No. 11/406,939 filed on April 18, 2006.
	93.	Application No. 11/412,738 filed on April 26, 2006.
	94.	Application No. 11/224,808 filed on September 13, 2005.
	95.	Application No. 11/557,185 filed on November 7, 2006.
	96.	Application No. 11/306,952 filed on January 16, 2007.
	97.	Application No. 11/433,965 filed on May 15, 2007.
	98.	Ahmed et al., "Nitrided Thermal SiO2 for Thin Buried Gate Insulator in Dual Gate SOI-MOSFET", University/Government Industry Microelectronics Symposium, 1999 Proceedings of the Thirteenth Biennial Minneapolis, MN June 20-23, 1999, Piscatatway, NJ, IEEE, June 20, 1999, pages 43-46.
	99.	Ahmed et al., "Nitrided Thermal SiO2 for Use as Top and Bottom Gate Insulators in Self-Aligned Double Gate Silicon-on-Insulator Metal-Oxide-Semiconductor Field Effect Transistor", Journal of Vacuum Science & Technology B (Microelectronics and Nanometer Structures) AIP for American Vacuum Soc., Vol. 19, No. 3, May 2001, pages 800-806.
	100.	Celler et al., "Smart Cut TM. A guide to the Technology, the Process, the Products", SOITEC, July 2003, 1-8.
	101.	Celler et al., "Strained Silicon on Insulator. A quick Guide to the Technology, the Processes, the Products", SOITEC, July 2003, 1-4.

Examiner	Date Considered

102.	Joshi et al., "Oxynitride Gate Dielectrics for p+ Polysilicon Gate MOS Devices", IEEE Electron Devices Letters, Vol. 14, No. 12, December 1993, pages 560-562, XP000418671.
103.	Ling Liao et al., "Optical Transmission Losses in Plycrystalline Silicon Strip Waveguides: Effects on Waveguide Dimensions, Thermal Treatment Hydrogen Passivation, and Wavelength", Journal of Electronic Materials, Vol. 29, No. 12, 2002, 1380.
104.	Nishihara, Hiroshi, et al., "Optical Integrated Circuits", R.R. Donnelley & Sons Company, 1989, pp. 224-235.
105.	PNG et al., "Development of Small Silicon Modulators in Silicon-on Insulator (SOI)", Proceedings of the SPI, SPIE, Bellingham, VA, Vol. 4997, 2003, pages 190-197.
106.	Reed, G.T., et al., "Silicon on Insulator Optical Waveguides Formed by Direct Wafer Bonding", Materials Science and Engineering B, Elsevier Sequoia, Lausame, Ch. Vol. B15, no. 2, 11-01-92, pages 156-159.
107.	Samara-Rubio D. et al., "A Gigahertz Silicon-on-Insulator Mach-Zehnder Modulator", Optical Fiber Communication Conference, 2004. OFC 2004 Los Angeles, CA USA, Feb. 23-25, 2004, IEEE, 26 February 2004, pp. 701-703, XP10745963.
108.	Singh Jagar et al., "Design Methodology of the High Performance Large-Grain Polysilicon MOSFET", IEEE Transactions on Electron Devices, Vol. 49, No. 5, May 2002, 795-801.
109.	Waldron et al., "Optical Modulator in Silicon-on-Insulator with a Low Thermal Signature", J. Vac. Sci. Thechnol. A 22(3) May/June 2004, 2004 American Vacuum Society.